

ABSTRACT OF THE DISCLOSURE

A method for manufacturing a semiconductor package, the method including the steps of attaching a bottom surface of a semiconductor wafer to a first 5 supporting member, forming a through hole in the semiconductor wafer, separating the semiconductor wafer from the first supporting member, forming an insulating layer on at least the bottom surface of the semiconductor wafer and the inner wall of the 10 through hole, forming a conducting layer underneath the semiconductor wafer, the conducting layer spanning at least the bottom of the through hole; and forming a conductive member in the through hole and in electrical contact with the conducting layer.